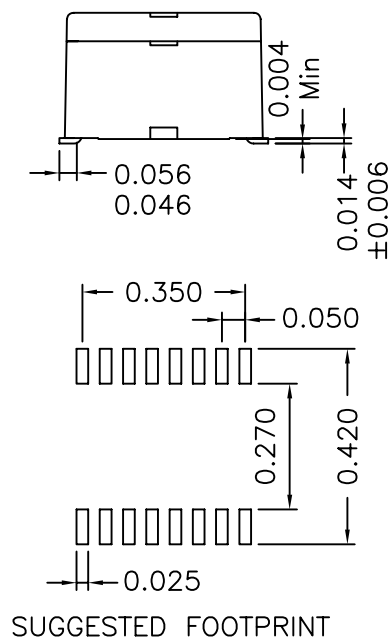
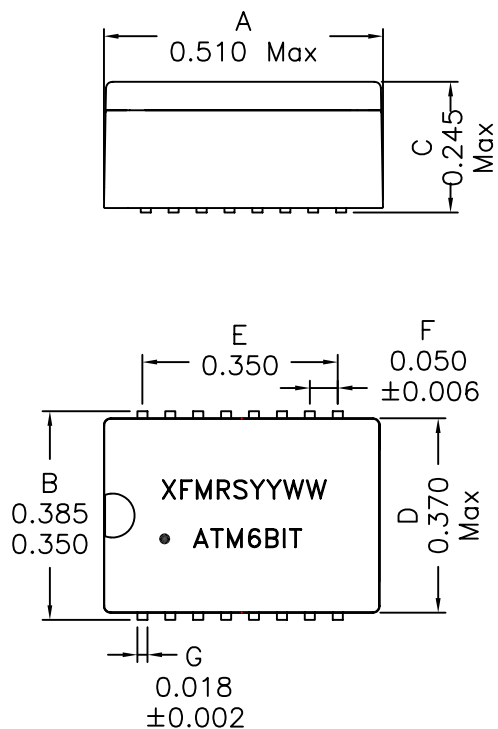
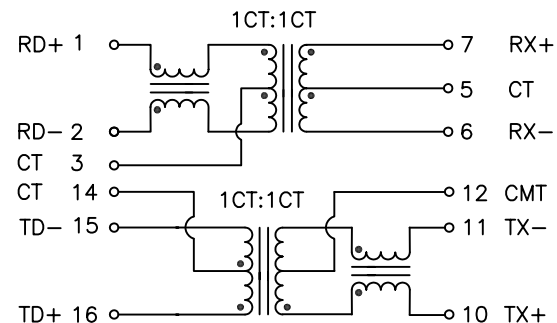


1. Mechanical Dimensions:



2. Schematic:



3. Electrical Specifications: @25°C

Isolation Voltage: 1500 Vrms

CHIP SIDE OCL: 350uH Min @100KHz 0.1V 8mA

Rise Time (10-90%): 4.0ns Typ

Insertion Loss (100KHz-100MHz): -1.0dB Max

Return Loss: 1-30MHz 40MHz 50MHz 60MHz-80MHz
-20dB -20dB -18dB -14dB Typ.

CMRR: 30MHz 60MHz 100MHz
-37dB -30dB -27dB (Typ)

CROSSTALK: 30MHz 60MHz 100MHz
-50dB -40dB -40dB (Min)

CHIP SIDE Q: 5 Min @10KHz 50mV

Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC. REV. B/1

PROPRIETARY

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XFMRS Inc. www.XFMRS.com		Title: HIGH SPEED LAN MAGNETICS	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in Inch		P/N: XFATM6BIT	
		REV. B	
		DWN.	Mei Chen
SHEET 1 OF 1		CHK.	YK Liao
		APP.	BW
		Sep-02-11	